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# S-파라미터 측정을 통한 MOSFET 캐리어 속도의 고온 종속 SPICE 모델링

( High Temperature Dependent SPICE Modeling for Carrier Velocity in  
MOSFETs Using Measured S-Parameters )

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## 요약

0.18 $\mu$ m deep n-well 벌크 NMOSFET에서 측정된 차단주파수  $f_T$ 의 고온종속성을 모델화하기 위해, 측정된 S-파라미터를 사용한 정확한 RF 방법으로 30 $^{\circ}$ C에서 250 $^{\circ}$ C까지 전자속도 고온 데이터가 추출되었다. 이러한 추출데이터를 사용하여 개선된 온도종속 전자속도 방정식이 높은 온도의 범위에서 생기는 기존 방정식의 모델링 오차를 없애기 위해 개발되었으며 BSIM3v3 SPICE RF 모델에 구현되었다. 개선된 온도 종속 방정식은 기존 모델보다 30 $^{\circ}$ C에서 250 $^{\circ}$ C까지 측정된  $f_T$ 와 더 잘 일치하였으며, 이는 개선된 방정식의 정확성을 입증한다.

## Abstract

In order to model the high temperature dependence of the cutoff frequency  $f_T$  in 0.18 $\mu$ m deep n-well isolated bulk NMOSFET, high temperature data of electron velocity of bulk MOSFETs from 30 $^{\circ}$ C to 250 $^{\circ}$ C are obtained by an accurate RF extraction method using measured S-parameters. From these data, an improved temperature-dependent electron velocity equation is developed and implemented in a BSIM3v3 SPICE model to eliminate modeling error of a conventional one in the high temperature range. Better agreement with measured  $f_T$  data from 30 $^{\circ}$ C to 250 $^{\circ}$ C are achieved by using the SPICE model with the improved equation rather than the conventional one, verifying its accuracy of the improved one.

**Keywords :** high temperature, MOSFET, carrier velocity, SPICE modeling, S-parameters

## I. INTRODUCTION

With the rapidly growing personal wireless communication markets, bulk CMOS technology becomes very popular due to strong possibilities for integrating baseband, intermediate frequency, and RF module as one-chip<sup>[1]</sup>. It is recently reported that the use of deep n-well isolated bulk NMOSFETs with

body-tied source is very promising for high temperature RF applications, because it has lower leakage current and better RF performance than Partially-Depleted SOI NMOSFETs<sup>[2]</sup>. In particular, deep n-well MOSFET technology might be emerging as commercially better solution, mainly due to lower cost than SOI. In general, the cutoff frequency ( $f_T$ ) and the maximum oscillation frequency ( $f_{max}$ ) are used as measures that display RF performance of MOSFETs. Thus, accurate modeling of high temperature-dependent  $f_T$  should be performed to predict the high-speed and RF performance of MOSFETs in high temperature operation. The value

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of  $f_T$  determining the maximum device speed is ultimately limited by the carrier velocity ( $v_{eff}$ ) under the velocity saturation region. Thus,  $v_{eff}$  is the most important parameter for SPICE modeling of  $f_T$  in MOSFET. Due to the reduction of  $v_{eff}$  at high temperatures,  $f_T$  decreases with increasing temperature<sup>[3~4]</sup>. In the BSIM3v3 SPICE model<sup>[5]</sup>, the linearly decreasing temperature-dependent  $v_{eff}$  equation is used, but produces inaccuracy in modeling  $v_{eff}$  data in the wide range of high temperatures<sup>[6]</sup>.

Therefore, in this paper, accurate high temperature SPICE modeling process in 0.18 $\mu$ m deep n-well isolated bulk NMOSFET from 30 $^{\circ}$ C to 250 $^{\circ}$ C is presented in detail by developing an improved temperature-dependent  $v_{eff}$  equation using a RF direct extraction method based on the extraction of the gate-source capacitance and transconductance from measured S-parameters.

## II. PARAMETER EXTRACTION

S-parameters are measured on multi-finger deep n-well isolated bulk NMOSFETs with various gate length  $L_g$  at the unit finger width of  $W_u=2.5\mu$ m and the number of gate finger of  $N_f=16$  under the source-bulk tied configuration as the wafer is heated from 30 $^{\circ}$ C to 250 $^{\circ}$ C using a hot chuck. The accurate de-embedding procedure using "open" and "short" test patterns was carried out to remove pad and interconnection parasitics from measured S-parameters<sup>[7]</sup>.

According to MOS device physics, a maximum value of  $f_T$  in the velocity saturation region is roughly expressed as  $v_{eff}/(2\pi L_g)$ . In order to model the temperature-dependent  $f_T$  behavior accurately,  $v_{eff}$  is extracted by using the following RF method.

In order to extract  $v_{eff}$  in the velocity saturation region, the following equation<sup>[8]</sup> is used.

$$v_{eff} = g_{mi}/K \tag{1}$$

where  $g_{mi}$  is the intrinsic transconductance and K is obtained by the slope of the best regression line of

$C_{gs}$  versus  $L_g$ . The equation (1) allows us to extract  $v_{eff}$  without the difficult extraction of the parasitic gate-source capacitance  $C_p$  and the effective channel length  $L_{eff}$ . The velocity saturation condition of  $\partial v_{eff}/\partial V_{gs} = \partial g_m/\partial V_{gs} = 0$  can be satisfied at the value of  $V_{gs}$  where  $g_m$  versus  $V_{gs}$  at high  $V_{ds}$  becomes a maximum value<sup>[8]</sup>. The bias of  $V_{gs}=V_{ds}=1V$  is applied in this work to satisfy the condition of  $\partial g_m/\partial V_{gs} = 0$ .

The values of  $g_{mi}$  and  $C_{gs}$  are extracted only using measured S-parameters without extra DC or C-V measurements. Fig. 1 shows a small-signal MOSFET equivalent circuit<sup>[9]</sup> used for the accurate extraction. In this figure, the transconductance is given by  $g_m=g_{mi}\cdot\exp(-j\omega\tau)$  where  $\tau$  is a phase delay.  $R_g$ ,  $R_d$  and  $R_s$  are the gate, drain and source resistance, respectively. For the intrinsic elements,  $C_{gs}$  is the gate-source capacitance,  $C_{gd}$  is the gate-drain capacitance,  $C_{ds}$  is the drain-source capacitance, and  $R_{ds}$  is the drain-source channel resistance.

In order to extract  $g_{mi}$  and  $C_{gs}$  accurately, external parasitic elements in Fig. 1 should be removed from the measured S-parameters. Thus, in this study, the following accurate RF extraction technique has been applied. The drain resistance extraction based on zero-bias measurement<sup>[10]</sup> has been performed by finding y-intercept of the following equation approximated in the high frequency range:

$$\text{Real}( Z_{22} - Z_{12} ) \approx R_d + A_d \cdot \omega^{-2} \tag{2}$$

where  $A_d$  is expressed as functions of intrinsic

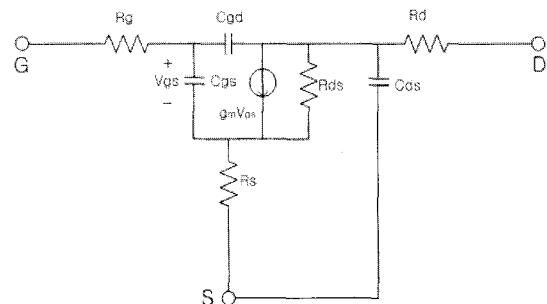


그림 1. MOSFET 소신호 모델.  $g_m=g_{mi} \cdot \exp(-j\omega\tau)$   
 Fig. 1. A small-signal equivalent circuit model for a MOSFET.  $g_m=g_{mi} \cdot \exp(-j\omega\tau)$ .

parameters, and is a constant value at fixed bias.

After  $R_d$  was subtracted from measured S-parameters to obtain  $Y^c$ -parameters,  $C_{ds}$  is directly extracted by:

$$C_{ds} = (1/\omega) \cdot \text{Imag}(Y_{22}^c + Y_{12}^c) \quad (3)$$

After the extracted  $C_{ds}$  was subtracted from the  $Y^c$ -parameters to obtain  $Z^d$ -parameters,  $R_g$  is extracted by finding y-intercept of the following equation approximated at high frequencies:

$$\text{Real}(Z_{11}^d - Z_{12}^d) \approx R_g + A_g \cdot \omega^{-2} \quad (4)$$

where  $A_g$  is a function of intrinsic parameters, and independent of frequency.

The  $R_s$  value is extracted by obtaining y-intercept of  $\text{Real}(Z_{11} - Z_{12})$  vs.  $\omega^{-2}$  for a test MOSFET where source and gate are interchanged. After  $Y^i$ -parameters are determined by subtracting  $R_s$  and  $R_g$  from the  $Z^d$ -parameters,  $g_{mi}$  and  $C_{gs}$  are extracted by the following analytical equations;

$$g_{mi} = |Y_{21}^i - Y_{12}^i| \quad (5)$$

$$C_{gs} = (1/\omega) \cdot \text{Imag}(Y_{11}^c + Y_{12}^c) \quad (6)$$

As shown in Figs. 2 and 3, the extracted values of  $g_{mi}$  and  $C_{gs}$  are plotting as a function of frequency and seem to be nearly frequency-independent up to 10GHz, verifying the accuracy of the parameter

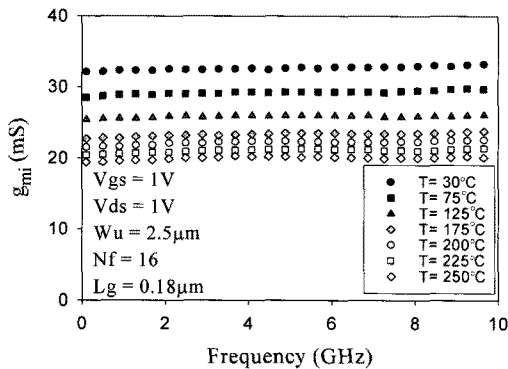


그림 2. 온도의 변화에 따라 추출된  $g_{mi}$  대 주파수 그래프

Fig. 2. The extracted data of  $g_{mi}$  versus frequency with varying temperature.(그림이 반전됨)

extraction.

As the temperature increases,  $g_{mi}$  is greatly decreased in Fig. 2, but  $C_{gs}$  is very slightly decreased

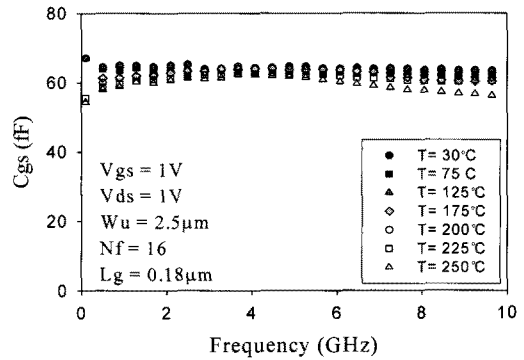


그림 3. 온도의 변화에 따라 추출된  $C_{gs}$  대 주파수 그래프

Fig. 3. The extracted data of  $C_{gs}$  versus frequency with varying temperature. (그림이 반전됨)

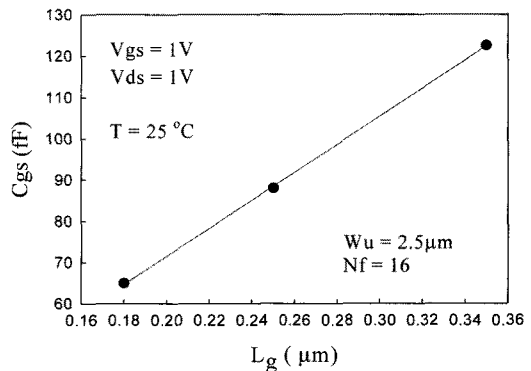


그림 4.  $L_g$ 의 함수로 그린 추출된  $C_{gs}$  데이터

Fig. 4. Extracted data of  $C_{gs}$  as a function of  $L_g$ .(그림이 반전됨)

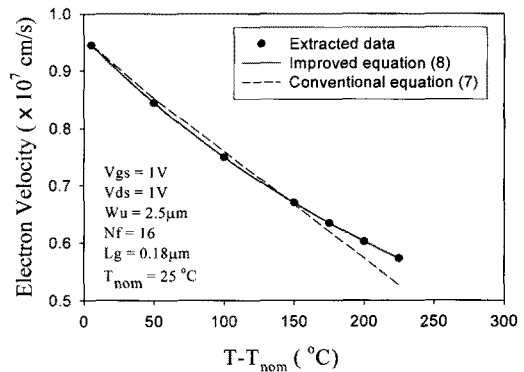


그림 5. 추출된  $v_{eff}$ 와 기존 및 개선된 방정식으로 모델된  $v_{eff}$ 와의 비교

Fig. 5. Comparison of extracted  $v_{eff}$  data with modeled curves using improved and conventional equations.(그림이 반전됨)

in Fig. 3. In the  $v_{eff}$  extraction, it is also assumed that the temperature-dependence of series resistances and  $C_{ds}$  are much smaller than that of  $g_{mi}$ . The value of  $K$  is determined from the slope of the best regression for  $C_{gs}$  versus  $L_g$  in Fig. 4 and the extracted values of  $v_{eff}$  using (1) are shown in Fig. 5.

### III. SPICE MODELING

Fig. 6 shows a modified BSIM3v3 RF model<sup>[11]</sup> suited for high-frequency circuit applications, where parasitic gate capacitances ( $C_{gsz}$ ,  $C_{gdx}$ ) and parasitic resistances ( $R_g$ ,  $R_{sub}$ ,  $R_{de}$ , and  $R_{se}$ ) are externally added to an original BSIM3v3 SPICE model<sup>[5]</sup>. The parasitic elements are determined by optimizing these values to obtain the closest fit between measured and modeled S-parameters.

In order to model the temperature-dependence of  $v_{eff}$ , the following empirical equation is conventionally used in BSIM3v3 and BSIM4 models.

$$v_{eff} = V_{sat}(T) = V_{sat}(T_{nom}) - A_T(T/T_{nom} - 1) \quad (7)$$

where  $V_{sat}(T_{nom})$  is the saturation velocity at room temperature and  $A_T$  is the linear temperature coefficient for saturation velocity.

However, this conventional equation may be valid in the narrow range of temperature, but produces inaccuracy in modeling the reduced decreasing rate of  $v_{eff}$  data in the high temperature in Fig. 5. Thus, in order to improve this modeling of  $v_{eff}$  data, an

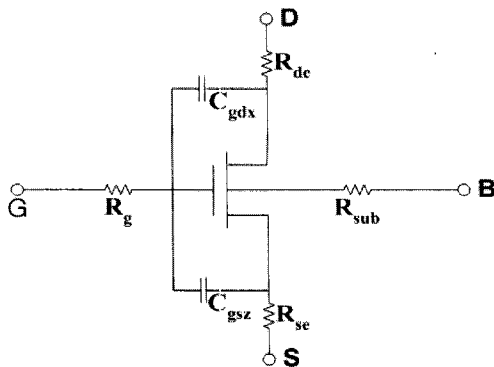


그림 6. BSIM3v3 RF SPICE 모델  
Fig. 6. BSIM3v3 RF SPICE model.

exponentially decreasing temperature-dependent equation with a constant value is developed as follows:

$$v_{eff} = [V_{sat}(T_{nom}) - V_{sat0}]e^{-B_T \cdot (T/T_{nom} - 1)} + V_{sat0} \quad (8)$$

where  $V_{sat0}$  is the minimum saturation velocity at the infinite temperature and  $B_T$  is the exponential temperature coefficient for  $v_{eff}$ .

To verify the improved  $v_{eff}$  equation, the high temperature-dependent  $f_T$  data of bulk NMOSFETs with  $L_g=0.18\mu m$  are plotted in Fig. 7. As shown in Fig. 7, it is observed the decreasing rate of  $f_T$  becomes lower at higher temperatures beyond 125°C. The decreasing  $f_T$  at higher temperatures can be explained by the reduction of  $v_{eff}$  in Fig. 5. In Figs. 7 and 8, the BSIM3v3 RF model including the improved

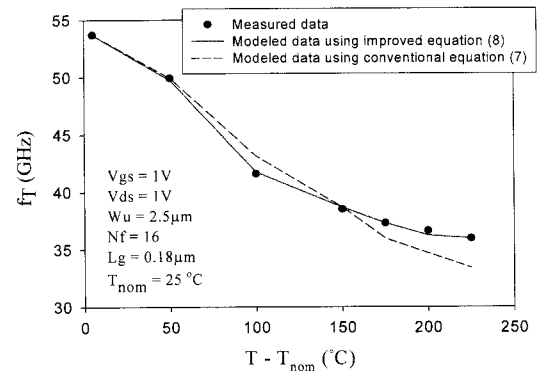


그림 7. 기존 및 개선된 방정식을 사용한 모델값과 측정  $f_T$  데이터

Fig. 7. Measured  $f_T$  data with modeled curves using improved and conventional equations.(그림이 반전됨)

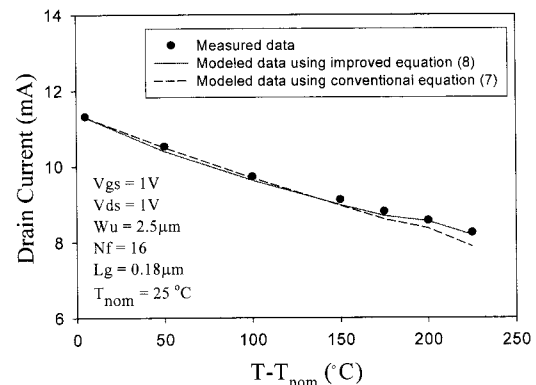


그림 8. 기존 및 개선된 방정식을 사용한 모델값과 측정  $I_{ds}$  데이터

Fig. 8. Measured  $I_{ds}$  data with modeled curves using improved and conventional equations.(그림이 반전됨)

$v_{\text{eff}}$  equation is verified to be accurate by finding better agreement with measured  $f_T$  and drain current  $I_{\text{ds}}$  data than the conventional one, respectively.

#### IV. CONCLUSIONS

In order to model the high temperature dependence of  $f_T$  from 30°C to 250°C on 0.18 $\mu\text{m}$  deep n-well isolated bulk NMOSFET, the high temperature data of  $v_{\text{eff}}$  have been extracted using a RF method based on the accurate small-signal modeling of measured S-parameters. To reduce the error of the conventional linear SPICE equation in modeling this temperature dependence, the improved temperature dependent  $v_{\text{eff}}$  one with exponentially decreasing behavior has been implemented in a modified BSIM3v3 SPICE RF model and its accuracy is validated by observing good agreements with extracted  $I_{\text{ds}}$  and  $f_T$  data from 30°C to 250°C.

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